molex

Part Number : 762910068
Product Description : EdgeLine CoPlanar
Connector, 6 Gbps, 0.75mm Pitch, 1.57mm PCB
Thickness, 68 Circuits
Series Number : 76291
Status : Active
Product Category : Card Edge Connectors

Documents & Resources

Drawings

762910068_sd.pdf

PK-76291-001-001.pdf

SP-76291-0002-001.zip

Specifications

AS-76291-001-001.pdf

AS-76291-002-001.pdf

PS-76291-001-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 44; 34; 33
China RoHS	⊕ per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)4165-DC (25 June 2025)
EU RoHS	Compliant per EU 2015/863

Compliance Statements
- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents
- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest
- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	Card Edge Connectors
Series	76291
Description	EdgeLine CoPlanar Connector, 6 Gbps, 0.75mm Pitch, 1.57mm PCB Thickness, 68 Circuits
Component Type	Edgecard to PCB
Product Name	EdgeLine
UPC	883906112745

Electrical

Current - Maximum per Contact	1.5A
Data Rate	5.0-12.0 Gbps
High Power Bay (30.0A or more)	No
Voltage - Maximum	50V AC (RMS)/DC

Physical

Circuits (Loaded)	68
Circuits (maximum)	68
Color - Resin	Black
Durability (mating cycles max)	200
Edge Card Thickness	1.57mm
Entry Angle	N/A

Keying to Mating Part	N/A
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	9.320/g
Orientation	Coplanar
Packaging Type	Tray
PCB Locator	No
PCB Thickness - Recommended	2.79mm
Pitch - Mating Interface	0.75mm
Pitch - Termination Interface	0.75mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm
Polarized to Mating Part	Yes
(p)ower-(s)ignal Configuration	68s - 0p
Temperature Range - Operating	-40° to +85°C
Termination Interface Style	Through Hole - Compliant Pin

Solder Process Data

Lead-Free Process Capability	N/A

Application Tooling

This document was generated on Aug 04, 2025